


MATERIAL DECLARATION SHEET



Material Number	CRM0805 Series (less than 1Ω)			
Product Line	High power lead free chip resistors			
Compliance Date	09/01/2016			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	4.1120	Aluminum oxide	1344-28-1	96	81.075	84.453
				Silicon dioxide	14808-60-7	2	1.689	
				Magnesium oxide	1309-48-4	2	1.689	
2	Top conductor	Silver	0.0817	Silver	7440-22-4	100	1.678	1.678
3	Bottom conductor	Silver	0.0482	Silver	7440-22-4	100	0.990	0.990
4	Resistor	Ruthenium Oxide	0.0490	Palladium	7440-05-3	40	0.402	1.006
				Silver	7440-22-4	35	0.352	
				Ruthenium(IV) oxide	12036-10-1	15	0.151	
				Silicon dioxide	14808-60-7	10	0.101	
5	First encapsulating	Glass	0.0467	Glass	65997-17-3	92	0.882	0.959
				Chromium(III) oxide	1308-38-9	8	0.077	
6	Overcoat	Resin	0.1172	Resin	25036-25-3	100	2.407	2.407
7	Side conductor	Silver	0.1707	Silver	7440-22-4	85	2.980	3.506
				Resin	9003-36-5	15	0.526	
8	Plating (Middle)	Nickel	0.0925	Nickel	7440-02-0	100	1.900	1.900
9	Plating (Outer)	Tin	0.1388	Tin	7440-31-5	100	2.851	2.851
10	Marking	Resin	0.0122	Resin	29690-82-2	70	0.175	0.250
				Titanium oxide	1317-80-2	30	0.075	
			Total weight			4.869		

This Document was updated on: 09/01/2016

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.